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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

2 0 0 0 0 0	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I ² C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	35
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 13x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16gp304-i-pt

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Referenced Sources

This device data sheet is based on the following individual chapters of the *"dsPlC33F/PlC24H Family Reference Manual"*. These documents should be considered as the general reference for the operation of a particular module or device feature.

Note 1: To access the documents listed below, browse to the documentation section of the dsPIC33FJ32GP204 product page of the Microchip web site (www.microchip.com).

> In addition to parameters, features, and other documentation, the resulting page provides links to the related family reference manual sections.

- Section 1. "Introduction" (DS70197)
- Section 2. "CPU" (DS70204)
- Section 3. "Data Memory" (DS70202)
- Section 4. "Program Memory" (DS70202)
- Section 5. "Flash Programming" (DS70191)
- Section 6. "Interrupts (DS70184)
- Section 7. "Oscillator" (DS70186)
- Section 8. "Reset" (DS70192)
- Section 9. "Watchdog Timer and Power-Saving Modes" (DS70196)
- Section 10. "I/O Ports" (DS70193)
- Section 11. "Timers" (DS70205)
- Section 12. "Input Capture" (DS70198)
- Section 13. "Output Compare" (DS70209)
- Section 16. "Analog-to-Digital Converter (ADC)" (DS70183)
- Section 17. "UART" (DS70188)
- Section 18. "Serial Peripheral Interface (SPI)" (DS70206)
- Section 19. "Inter-Integrated Circuit™ (I²C™)" (DS70195)
- Section 23. "CodeGuard™ Security" (DS70199)
- Section 25. "Device Configuration" (DS70194)

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS

- Note 1: This data sheet summarizes the features of the dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the "dsPIC33F/PIC24H Family Reference Manual". Please see the Microchip web site (www.microchip.com) for the latest dsPIC33F/PIC24H Family Reference Manual sections.
 - Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 family of 16-bit Digital Signal Controllers (DSCs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and Vss pins
 (see Section 2.2 "Decoupling Capacitors")
- All AVDD and AVSS pins (even if ADC module is not used)

(see Section 2.2 "Decoupling Capacitors")
• VCAP

(see Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)")

- MCLR pin (see Section 2.4 "Master Clear (MCLR) Pin")
- PGECx/PGEDx pins used for In-Circuit Serial Programming[™] (ICSP[™]) and debugging purposes (see Section 2.5 "ICSP Pins")
- OSC1 and OSC2 pins when external oscillator source is used

(see Section 2.6 "External Oscillator Pins")

Additionally, the following pins may be required:

• VREF+/VREF- pins used when external voltage reference for ADC module is implemented

Note: The AVDD and AVSS pins must be connected independent of the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSs is required.

Consider the following criteria when using decoupling capacitors:

- Value and type of capacitor: Recommendation of 0.1 μ F (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended that ceramic capacitors be used.
- Placement on the printed circuit board: The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- Handling high frequency noise: If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μ F to 0.001 μ F. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 μ F in parallel with 0.001 μ F.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

U-0	U-0	U-0	R/W-0	R/W-0	R-0	R-0	R-0
		_	US	EDT ⁽¹⁾		DL<2:0>	
bit 15	•						bit
R/W-0	R/W-0	R/W-1	R/W-0	R/C-0	R/W-0	R/W-0	R/W-0
SATA	SATB	SATDW	ACCSAT	IPL3 ⁽²⁾	PSV	RND	IF
bit 7							bit
Legend:		C = Clear on	v bit				
R = Readable	e bit	W = Writable	-	-n = Value at	POR	'1' = Bit is set	
0' = Bit is clea		'x = Bit is unk			nented bit, read		
bit 15-13	Unimplemen	ted: Read as	0'				
bit 12	-	tiply Unsigned		ol bit			
		ne multiplies a	0				
	0 = DSP engi	ne multiplies a	ire signed				
bit 11	EDT: Early DO	D Loop Termina	ation Control b	oit(1)			
	1 = Terminate 0 = No effect	e executing DO	loop at end of	f current loop it	eration		
bit 10-8	DL<2:0>: DO	Loop Nesting	Level Status b	its			
	111 = 7 DO Io	ops active					
	•						
	• 001 = 1 DO lo	on active					
	000 = 0 DO IO						
bit 7		Saturation Ena	ble bit				
		ator A saturatio					
bit 6		ator A saturation Saturation Ena					
		ator B saturatio					
		ator B saturation					
bit 5	SATDW: Data	a Space Write	from DSP Eng	ine Saturation	Enable bit		
		ce write satura					
	•	ce write satura					
bit 4		cumulator Satu		Select bit			
		ration (super s ration (normal	,				
bit 3		terrupt Priority		nit 3(2)			
		rrupt Priority L					
		rrupt Priority L	0				
bit 2	PSV: Program	n Space Visibi	ity in Data Spa	ace Enable bit			
	•	space visible i	•				
1.11.4	-	space not visit	-	ce			
bit 1		ng Mode Sele		1			
		onventional) ro (convergent)					
bit 0		Fractional Mu	-				
	1 = Integer m	ode enabled fo	or DSP multipl	y ops			
	- Erectione	l mada anabla	d for DSP mul	tinly one			

2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

File Name		Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	16GP30 Bit 2	Bit 1	Bit 0	All
		2.0.10		2.0.10		2	2	2						2		2	2	Resets
RPOR0	06C0	_	_	_			RP1R<4:0>			—	_	_			RP0R<4:0>	•		0000
RPOR1	06C2	_	_	_			RP3R<4:0>			_	_	_			RP2R<4:0>	•		0000
RPOR2	06C4	_	_	_			RP5R<4:0>			_	_	_			RP4R<4:0>			0000
RPOR3	06C6		_				RP7R<4:0>				_	_			RP6R<4:0>	•		0000
RPOR4	06C8	_	_	_			RP9R<4:0>			_	_	_			RP8R<4:0>	•		0000
RPOR5	06CA		_			RP11R<4:0>			_	_	RP10R<4:0>			0000				
RPOR6	06CC		_			F	RP13R<4:0	>			_	_			RP12R<4:0	>		0000
RPOR7	06CE	_	_	_		F	RP15R<4:0	>		_	_	_			RP14R<4:0	>		0000
RPOR8	06D0	_	_	_		F	RP17R<4:0	>		_	_	_			RP16R<4:0	>		0000
RPOR9	06D2	_	_	_		F	RP19R<4:0	>		_	_	_			RP18R<4:0	>		0000
RPOR10	06D4		_			RP21R<4:0>			_	_	RP20R<4:0>			0000				
RPOR11	06D6	_	_			F	RP23R<4:0	>		_	_	_			RP22R<4:0	>		0000
RPOR12	06D8	_	_	_		F	RP25R<4:0	>		_	_	_			RP24R<4:0	>		0000

Legend:

x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.6.3 MODULO ADDRESSING APPLICABILITY

Modulo Addressing can be applied to the Effective Address (EA) calculation associated with any W register.

Address boundaries check for addresses equal to:

- The upper boundary addresses for incrementing buffers
- The lower boundary addresses for decrementing buffers

It is important to realize that the address boundaries also check for addresses less than or greater than these addresses. Address changes can, therefore, jump beyond boundaries and still be adjusted correctly.

Note: The modulo corrected effective address is written back to the register only when Pre-Modify or Post-Modify Addressing mode is used to compute the effective address. When an address offset (such as [W7+W2]) is used, Modulo Address correction is performed but the contents of the register remain unchanged.

4.7 Bit-Reversed Addressing

Bit-Reversed Addressing mode is intended to simplify data re-ordering for radix-2 FFT algorithms. It is supported by the X AGU for data writes only.

The modifier, which can be a constant value or register contents, is regarded as having its bit order reversed. The address source and destination are kept in normal order. Thus, the only operand requiring reversal is the modifier.

4.7.1 BIT-REVERSED ADDRESSING IMPLEMENTATION

Bit-Reversed Addressing mode is enabled in any of these situations:

- BWM bits (W register selection) in the MODCON register are any value other than '15' (the stack cannot be accessed using Bit-Reversed Addressing).
- The BREN bit is set in the XBREV register.
- The addressing mode used is Register Indirect with Pre-Increment or Post-Increment.

If the length of a bit-reversed buffer is $M = 2^N$ bytes, the last 'N' bits of the data buffer start address must be zeros.

XB<14:0> is the Bit-Reversed Address modifier, or 'pivot point', which is typically a constant. In the case of an FFT computation, its value is equal to half of the FFT data buffer size.

Note: All bit-reversed EA calculations assume word sized data (LSB of every EA is always clear). The XB value is scaled accordingly to generate compatible (byte) addresses.

When enabled, Bit-Reversed Addressing is executed only for Register Indirect with Pre-Increment or Post-Increment Addressing and word sized data writes. It will not function for any other addressing mode or for byte sized data, and normal addresses are generated instead. When Bit-Reversed Addressing is active, the W Address Pointer is always added to the address modifier (XB), and the offset associated with the Register Indirect Addressing mode is ignored. In addition, as word sized data is a requirement, the LSb of the EA is ignored (and always clear).

Note: Modulo Addressing and Bit-Reversed Addressing should not be enabled together. If an application attempts to do so, Bit-Reversed Addressing will assume priority when active for the X WAGU and X WAGU Modulo Addressing will be disabled. However, Modulo Addressing will continue to function in the X RAGU.

If Bit-Reversed Addressing has already been enabled by setting the BREN bit (XBREV<15>), a write to the XBREV register should not be immediately followed by an indirect read operation using the W register that has been designated as the bit-reversed pointer.

Symbol	Parameter	Value
VPOR	POR threshold	1.8V nominal
TPOR	POR extension time	30 μs maximum
VBOR	BOR threshold	2.5V nominal
TBOR	BOR extension time	100 μs maximum
TPWRT	Programmable power-up time delay	0-128 ms nominal
TFSCM	Fail-Safe Clock Monitor Delay	900 μs maximum

TABLE 6-2: OSCILLATOR PARAMETERS

Note: When the device exits the Reset condition (begins normal operation), the device operating parameters (voltage, frequency, temperature, etc.) must be within their operating ranges, otherwise the device may not function correctly. The user application must ensure that the delay between the time power is first applied, and the time SYSRST becomes inactive, is long enough to get operating parameters within all specification.

6.4 Power-on Reset (POR)

A Power-on Reset (POR) circuit ensures the device is reset from power-on. The POR circuit is active until VDD crosses the VPOR threshold and the delay TPOR has elapsed. The delay TPOR ensures the internal device bias circuits become stable.

The device supply voltage characteristics must meet the specified starting voltage and rise rate requirements to generate the POR. Refer to Section 22.0 "Electrical Characteristics" for details.

The POR status (POR) bit in the Reset Control (RCON<0>) register is set to indicate the Power-on Reset.

6.4.1 Brown-out Reset (BOR) and Power-up timer (PWRT)

The on-chip regulator has a Brown-out Reset (BOR) circuit that resets the device when the VDD is too low (VDD < VBOR) for proper device operation. The BOR circuit keeps the device in Reset until VDD crosses VBOR threshold and the delay TBOR has elapsed. The delay TBOR ensures the voltage regulator output becomes stable.

The BOR status bit in the Reset Control register (RCON<1>) is set to indicate the Brown-out Reset.

The device will not run at full speed after a BOR as the VDD should rise to acceptable levels for full-speed operation. The PWRT provides power-up time delay (TPWRT) to ensure that the system power supplies have stabilized at the appropriate levels for full-speed operation before the SYSRST is released.

The power-up timer delay (TPWRT) is programmed by the Power-on Reset Timer Value Select bits (FPWRT<2:0>) in the POR Configuration register (FPOR<2:0>), which provide eight settings (from 0 ms to 128 ms). Refer to **Section 19.0 "Special Features"** for further details.

Figure 6-3 shows the typical brown-out scenarios. The reset delay (TBOR + TPWRT) is initiated each time VDD rises above the VBOR trip point

REGISTER	7-8: IEC0:	INTERRUPT	ENABLE CO	ONTROL REC	GISTER 0		
U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
_	_	AD1IE	U1TXIE	U1RXIE	SPI1IE	SPI1EIE	T3IE
bit 15							bit 8
R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
T2IE	OC2IE	IC2IE	0-0	T1IE	OC1IE	IC1IE	INTOIE
bit 7	UUZIE	ICZIE		111	OCTIE	ICTIE	bit (
Legend:							
R = Readable	e bit	W = Writable	bit	U = Unimplen	nented bit, rea	d as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is clea	ared	x = Bit is unkn	own
bit 15-14	Unimplemen	ted: Read as '	0'				
bit 13	AD1IE: ADC1	Conversion C	complete Inter	rupt Enable bit			
	1 = Interrupt r	equest enable	d				
	0 = Interrupt r	equest not en	abled				
bit 12		RT1 Transmitte	•	able bit			
	•	equest enable equest not ena					
bit 11		RT1 Receiver I		e hit			
bit II		equest enable					
		equest not en					
bit 10	SPI1IE: SPI1	Event Interrup	t Enable bit				
		equest enable					
h # 0		equest not en					
bit 9		1 Error Interru equest enable					
		request not enable					
bit 8	T3IE: Timer3	Interrupt Enab	le bit				
		equest enable equest not ena					
bit 7	T2IE: Timer2	Interrupt Enab	le bit				
		equest enable equest not en					
bit 6	•	ut Compare Ch		upt Enable bit			
		equest enable equest not en					
bit 5	IC2IE: Input C	Capture Chann	el 2 Interrupt I	Enable bit			
		equest enable equest not ena					
bit 4	Unimplemen	ted: Read as '	0'				
bit 3	T1IE: Timer1	Interrupt Enab	le bit				
	•	equest enable equest not en					
bit 2	OC1IE: Output	ut Compare Ch	annel 1 Interr	upt Enable bit			
	1 = Interrupt r 0 = Interrupt r	equest enable	d				

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—			ILF	R<3:0>	
bit 15							bit 8
U-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
				VECNUM<6:0	>		
bit 7							bit (
Legend:							
R = Readabl	le bit	W = Writable	bit	U = Unimplen	nented bit, rea	ad as '0'	
-n = Value at	t POR	'1' = Bit is set		'0' = Bit is clea	ared	x = Bit is unkr	nown
bit 11-8 bit 7	1111 = CPU • • • • • • • • • • • • • • • • • • •	Iew CPU Interrup J Interrupt Priorit J Interrupt Priorit J Interrupt Priorit ented: Read as '(y Level is 15 y Level is 1 y Level is 0	el bits			
	•						
bit 6-0	0111111 = • • 0000001 =	:0>: Vector Num Interrupt Vector Interrupt Vector Interrupt Vector	pending is nu pending is nu	mber 135 mber 9			

REGISTER 7-19: INTTREG: INTERRUPT CONTROL AND STATUS REGISTER

8.1 CPU Clocking System

The dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 device provides seven system clock options:

- · Fast RC (FRC) Oscillator
- FRC Oscillator with PLL
- Primary (XT, HS or EC) Oscillator
- Primary Oscillator with PLL
- · Secondary (LP) Oscillator
- · Low-Power RC (LPRC) Oscillator
- · FRC Oscillator with postscaler

8.1.1 SYSTEM CLOCK SOURCES

8.1.1.1 Fast RC

The Fast RC (FRC) internal oscillator runs at a nominal frequency of 7.37 MHz. User software can tune the FRC frequency. User software can optionally specify a factor (ranging from 1:2 to 1:256) by which the FRC clock frequency is divided. This factor is selected using the FRCDIV<2:0> bits (CLKDIV<10:8>).

8.1.1.2 Primary

The primary oscillator can use one of the following as its clock source:

- XT (Crystal): Crystals and ceramic resonators in the range of 3 MHz to 10 MHz. The crystal is connected to the OSC1 and OSC2 pins.
- HS (High-Speed Crystal): Crystals in the range of 10 MHz to 40 MHz. The crystal is connected to the OSC1 and OSC2 pins.
- EC (External Clock): The external clock signal is directly applied to the OSC1 pin.

8.1.1.3 Secondary

The secondary (LP) oscillator is designed for low power and uses a 32.768 kHz crystal or ceramic resonator. The LP oscillator uses the SOSCI and SOSCO pins.

8.1.1.4 Low-Power RC

The Low-Power RC (LPRC) internal oscillator runs at a nominal frequency of 32.768 kHz. It is also used as a reference clock by the Watchdog Timer (WDT) and Fail-Safe Clock Monitor (FSCM).

8.1.1.5 FRC

The clock signals generated by the FRC and primary oscillators can be optionally applied to an on-chip Phase Locked Loop (PLL) to provide a wide range of output frequencies for device operation. PLL configuration is described in Section 8.1.3 "PLL Configuration".

The FRC frequency depends on the FRC accuracy (see Table 22-18) and the value of the FRC Oscillator Tuning register (see Register 8-4).

8.1.2 SYSTEM CLOCK SELECTION

The oscillator source used at a device Power-on Reset event is selected using Configuration bit settings. The Oscillator Configuration bit settings are located in the Configuration registers in the program memory. (Refer to Section 19.1 "Configuration Bits" for further details.) The Initial Oscillator Selection Configuration bits, FNOSC<2:0> (FOSCSEL<2:0>), and the Primary Oscillator Mode Select Configuration bits. POSCMD<1:0> (FOSC<1:0>), select the oscillator source that is used at a Power-on Reset. The FRC primary oscillator is the default (unprogrammed) selection.

The Configuration bits allow users to choose among 12 different clock modes, shown in Table 8-1.

The output of the oscillator (or the output of the PLL if a PLL mode has been selected) Fosc is divided by 2 to generate the device instruction clock (FcY) and the peripheral clock time base (FP). FcY defines the operating speed of the device, and speeds up to 40 MHz are supported by the dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 architecture.

Instruction execution speed or device operating frequency, FCY, is given by:

EQUATION 8-1: DEVICE OPERATING FREQUENCY

$$FCY = \frac{FOSC}{2}$$

8.1.3 PLL CONFIGURATION

The primary oscillator and internal FRC oscillator can optionally use an on-chip PLL to obtain higher speeds of operation. The PLL provides significant flexibility in selecting the device operating speed. A block diagram of the PLL is shown in Figure 8-2.

The output of the primary oscillator or FRC, denoted as 'FIN', is divided down by a prescale factor (N1) of 2, 3, ... or 33 before being provided to the PLL's Voltage Controlled Oscillator (VCO). The input to the VCO must be selected in the range of 0.8 MHz to 8 MHz. The prescale factor 'N1' is selected using the PLLPRE<4:0> bits (CLKDIV<4:0>).

The PLL Feedback Divisor, selected using the PLLDIV<8:0> bits (PLLFBD<8:0>), provides a factor 'M', by which the input to the VCO is multiplied. This factor must be selected such that the resulting VCO output frequency is in the range of 100 MHz to 200 MHz.

The VCO output is further divided by a postscale factor 'N2.' This factor is selected using the PLLPOST<1:0> bits (CLKDIV<7:6>). 'N2' can be either 2, 4 or 8, and must be selected such that the PLL output frequency (Fosc) is in the range of 12.5 MHz to 80 MHz, which generates device operating speeds of 6.25-40 MIPS.

REGISTER 10-2: RPINR1: PERIPHERAL PIN SELECT INPUT REGISTER 1

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	
_	—	—	_	—	—	—	_	
bit 15							bit 8	
U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	
—	—	—	— INT2R<4:0>					
bit 7							bit 0	
Legend:								
R = Readab	le bit	W = Writable	bit	U = Unimple	mented bit, read	d as '0'		
-n = Value a	It POR	'1' = Bit is set		'0' = Bit is cleared x = Bit is un			nown	
bit 15-5	Unimpleme	nted: Read as '	0'					
	-				oorrooponding	DDn nin		
bit 4-0		: Assign Extern	ai menupi 2	(INTR2) to the	corresponding	RPITPIT		
	•	ut tied to Vss						
	11001 = Inp	ut tied to RP25						
	•							
	•							
	•							
	00001 - 100							

00001 = Input tied to RP1 00000 = Input tied to RP0

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1		
_	_				IC2R<4:0>				
bit 15							bit 8		
U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1		
	—	—			IC1R<4:0>				
bit 7							bit 0		
Legend:									
R = Readabl	le bit	W = Writable	bit	U = Unimpler	mented bit, rea	ad as '0'			
-n = Value at	n = Value at POR (1' = Bit is set (0' = Bit is cleared x = Bit is unknow								
	11001 = Inpu •	t tied to RP25							
	• 00001 = Inpu 00000 = Inpu	t tied to RP0							
bit 7-5	•	ted: Read as '							
bit 4-0	11111 = Inpu	ssign Input Ca t tied to Vss t tied to RP25	ipture 1 (IC1) i	to the correspo	onding RPn pir	n			
	00001 = Inpu 00000 = Inpu								

REGISTER 10-4: RPINR7: PERIPHERAL PIN SELECT INPUT REGISTER 7

REGISTER 10-14: RPOR4: PERIPHERAL PIN SELECT OUTPUT REGISTER 4

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
—	—	—	RP9R<4:0>							
bit 15							bit 8			
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
_	_	—			RP8R<4:0>					
bit 7	·		•				bit 0			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	l as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 Unimplemented: Read as '0'

bit 12-8 **RP9R<4:0>:** Peripheral Output Function is Assigned to RP9 Output Pin (see Table 10-2 for peripheral function numbers)

bit 7-5 Unimplemented: Read as '0'

bit 4-0 **RP8R<4:0>:** Peripheral Output Function is Assigned to RP8 Output Pin (see Table 10-2 for peripheral function numbers)

REGISTER 10-15: RPOR5: PERIPHERAL PIN SELECT OUTPUT REGISTER 5

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
_	—	—			RP11R<4:0>	>	
bit 15	•						bit 8
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—				RP10R<4:0>	>	
bit 7							bit 0
Legend:							
R = Readable	e bit	W = Writable I	oit	U = Unimpler	nented bit, rea	d as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	x = Bit is unkr	nown	
bit 15-13	Unimpleme	nted: Read as ')'				
bit 12-8	RP11R<4:0> eral function	: Peripheral Out numbers)	tput Functior	n is Assigned to	RP11 Output F	Pin (see Table 1	0-2 for periph-

bit 7-5 Unimplemented: Read as '0'

bit 4-0 **RP10R<4:0>:** Peripheral Output Function is Assigned to RP10 Output Pin (see Table 10-2 for peripheral function numbers)

13.2 Input Capture Registers

REGISTER 13-1: ICxCON: INPUT CAPTURE x CONTROL REGISTER

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	ICSIDL	-	—	—	_	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-0, HC	R-0, HC	R/W-0	R/W-0 R/W-0 R/V	
ICTMR	ICI<1:0>		ICOV	ICBNE			
bit 7							bit 0

Legend:		HC = C	leared in hardware
R = Readable bit	W = Writable bit	U = Unimplemented bit	, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14	Unimplemented: Read as '0'					
bit 13	ICSIDL: Input Capture Module Stop in Idle Control bit					
	 1 = Input capture module will halt in CPU Idle mode 0 = Input capture module will continue to operate in CPU Idle mode 					
bit 12-8	Unimplemented: Read as '0'					
bit 7	ICTMR: Input Capture Timer Select bits					
	 1 = TMR2 contents are captured on capture event 0 = TMR3 contents are captured on capture event 					
bit 6-5	ICI<1:0>: Select Number of Captures per Interrupt bits					
	 11 = Interrupt on every fourth capture event 10 = Interrupt on every third capture event 01 = Interrupt on every second capture event 					
	00 = Interrupt on every capture event					
bit 4	ICOV: Input Capture Overflow Status Flag bit (read-only)					
	 1 = Input capture overflow occurred 0 = No input capture overflow occurred 					
bit 3	ICBNE: Input Capture Buffer Empty Status bit (read-only)					
	 1 = Input capture buffer is not empty, at least one more capture value can be read 0 = Input capture buffer is empty 					
bit 2-0	ICM<2:0>: Input Capture Mode Select bits					
	 111 = Input capture functions as interrupt pin only when device is in Sleep or Idle mode (Rising edge detect only, all other control bits are not applicable.) 110 = Unused (module disabled) 101 = Capture mode, every 16th rising edge 					
	100 = Capture mode, every 4th rising edge					
	 011 = Capture mode, every rising edge 010 = Capture mode, every falling edge 					
	001 = Capture mode, every edge (rising and falling)					
	(ICI<1:0> bits do not control interrupt generation for this mode.)					
	000 = Input capture module turned off					

			EGISTER 3			
U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—			SAMC<4:0>	1)	
						bit
U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
		ADCS<	<7:0> ⁽²⁾			
						bit
bit	W = Writable b	t	U = Unimpler	mented bit, rea	ad as '0'	
OR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown
1 = ADC inter	nal RC clock					
	-					
11111 = 31 T. • • • • • • • • • • • • • • • • • • •	AD D					
11111111 = • • • • • • • • • • • • • •	Reserved					
	U-0 U-0 bit OR ADRC: ADC (1 = ADC inter 0 = Clock deri Unimplement SAMC<4:0>: 11111 = 31 T. 00001 = 1 TA 00000 = 0 TA ADCS<7:0>: 11111111 = 1 01000000 = 1	U-0 R/W-0 U-0 R/W-0 bit W = Writable bi OR '1' = Bit is set ADRC: ADC Conversion Cloc 1 = ADC internal RC clock 0 = Clock derived from system Unimplemented: Read as '0' SAMC<4:0>: Auto Sample Tin 11111 = 31 TAD 00001 = 1 TAD 00000 = 0 TAD ADCS<7:0>: ADC Conversion 1111111 = Reserved 01000000 = Reserved	U-0 R/W-0 R/W-0 ADCS bit W = Writable bit OR '1' = Bit is set ADRC: ADC Conversion Clock Source bit 1 = ADC internal RC clock 0 = Clock derived from system clock Unimplemented: Read as '0' SAMC<4:0>: Auto Sample Time bits ⁽¹⁾ 11111 = 31 TAD . <td>U-0 R/W-0 R/W-0 R/W-0 ADCS<7:0>⁽²⁾ ADCS<7:0>⁽²⁾ bit W = Writable bit U = Unimpler OR '1' = Bit is set '0' = Bit is cle ADRC: ADC Conversion Clock Source bit 1 = ADC internal RC clock 0 = Clock derived from system clock Unimplemented: Read as '0' SAMC<4:0>: Auto Sample Time bits⁽¹⁾ 11111 = 31 TAD . <tr tr=""></tr></td> <td>U-0 R/W-0 R/W-0 R/W-0 ADCS<7:0>⁽²⁾ bit W = Writable bit U = Unimplemented bit, res OR '1' = Bit is set '0' = Bit is cleared ADRC: ADC Conversion Clock Source bit 1 = ADC internal RC clock 0 = Clock derived from system clock Unimplemented: Read as '0' SAMC<4:0>: Auto Sample Time bits⁽¹⁾ 1111 = 31 TAD . . 00001 = 1 TAD ADCS<7:0>: ADC Conversion Clock Select bits⁽²⁾ 11111111 = Reserved .<</td> <td>- - SAMC<4:0>⁽¹⁾ U-0 R/W-0 R/W-0 R/W-0 R/W-0 ADCS<7:0>⁽²⁾ ADCS<7:0>⁽²⁾ bit bit W = Writable bit U = Unimplemented bit, read as '0' DRC: ADC Conversion Clock Source bit 1 = ADC internal RC clock 0 = Clock derived from system clock Unimplemented: Read as '0' SAMC<4:0>: Auto Sample Time bits⁽¹⁾ 11111 = 31 TAD</td>	U-0 R/W-0 R/W-0 R/W-0 ADCS<7:0> ⁽²⁾ ADCS<7:0> ⁽²⁾ bit W = Writable bit U = Unimpler OR '1' = Bit is set '0' = Bit is cle ADRC: ADC Conversion Clock Source bit 1 = ADC internal RC clock 0 = Clock derived from system clock Unimplemented: Read as '0' SAMC<4:0>: Auto Sample Time bits ⁽¹⁾ 11111 = 31 TAD . <tr tr=""></tr>	U-0 R/W-0 R/W-0 R/W-0 ADCS<7:0> ⁽²⁾ bit W = Writable bit U = Unimplemented bit, res OR '1' = Bit is set '0' = Bit is cleared ADRC: ADC Conversion Clock Source bit 1 = ADC internal RC clock 0 = Clock derived from system clock Unimplemented: Read as '0' SAMC<4:0>: Auto Sample Time bits ⁽¹⁾ 1111 = 31 TAD . . 00001 = 1 TAD ADCS<7:0>: ADC Conversion Clock Select bits ⁽²⁾ 11111111 = Reserved .<	- - SAMC<4:0> ⁽¹⁾ U-0 R/W-0 R/W-0 R/W-0 R/W-0 ADCS<7:0> ⁽²⁾ ADCS<7:0> ⁽²⁾ bit bit W = Writable bit U = Unimplemented bit, read as '0' DRC: ADC Conversion Clock Source bit 1 = ADC internal RC clock 0 = Clock derived from system clock Unimplemented: Read as '0' SAMC<4:0>: Auto Sample Time bits ⁽¹⁾ 11111 = 31 TAD

REGISTER 18-3: AD1CON3: ADC1 CONTROL REGISTER 3

NOTES:

TABLE 22-5: D	DC CHARACTERISTICS: OPERATING CURRENT (IDD)	
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DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended				
Parameter No. ⁽²⁾	Typical ⁽³⁾	Мах	Units	its Conditions			
Operating Cur	rent (IDD) ⁽¹⁾						
DC20d	20	30	mA	-40°C			
DC20a	19	22	mA	+25°C	3.3V	10 MIPS ⁽³⁾	
DC20b	19	25	mA	+85°C	3.3V		
DC20c	19	30	mA	+125°C]		
DC21d	28	40	mA	-40°C		16 MIPS ⁽³⁾	
DC21a	27	30	mA	+25°C	3.3V		
DC21b	27	32	mA	+85°C			
DC21c	27	36	mA	+125°C			
DC22d	33	50	mA	-40°C		20 MIPS ⁽³⁾	
DC22a	33	40	mA	+25°C	3.3V		
DC22b	33	40	mA	+85°C	- 3.3V		
DC22c	33	50	mA	+125°C			
DC23d	44	60	mA	-40°C		30 MIPS ⁽³⁾	
DC23a	43	50	mA	+25°C	3.3V		
DC23b	42	55	mA	+85°C	3.3V	30 WIF 3(*)	
DC23c	41	65	mA	+125°C]		
DC24d	55	75	mA	-40°C			
DC24a	54	65	mA	+25°C	2.21/		
DC24b	52	70	mA	+85°C	- 3.3V	40 MIPS	
DC24c	51	80	mA	+125°C			

Note 1: IDD is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDD measurements are as follows:

• Oscillator is configured in EC mode with PLL, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)

- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to Vss
- MCLR = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (defined PMDx bits are set to zero and unimplemented PMDx bits are set to one)
- CPU executing while (1) statement
- · JTAG is disabled
- 2: These parameters are characterized but not tested in manufacturing.
- 3: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

TABLE 22-32:SPIX SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING
REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended				
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Typ ⁽²⁾	Max	Units	Conditions
SP70	TscP	Maximum SCK Input Frequency	_		15	MHz	See Note 3
SP72	TscF	SCKx Input Fall Time	—	_		ns	See parameter DO32 and Note 4
SP73	TscR	SCKx Input Rise Time	—	_	—	ns	See parameter DO31 and Note 4
SP30	TdoF	SDOx Data Output Fall Time	—	_	—	ns	See parameter DO32 and Note 4
SP31	TdoR	SDOx Data Output Rise Time	—	_	—	ns	See parameter DO31 and Note 4
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	_		ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	_		ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	_	ns	—
SP50	TssL2scH, TssL2scL	$\overline{SSx} \downarrow$ to SCKx \uparrow or SCKx Input	120	—	—	ns	—
SP51	TssH2doZ	SSx	10	—	50	ns	—
SP52	TscH2ssH TscL2ssH	SSx after SCKx Edge	1.5 Tcy + 40	—	_	ns	See Note 4
SP60	TssL2doV	SDOx Data Output Valid after SSx Edge	—	—	50	ns	—

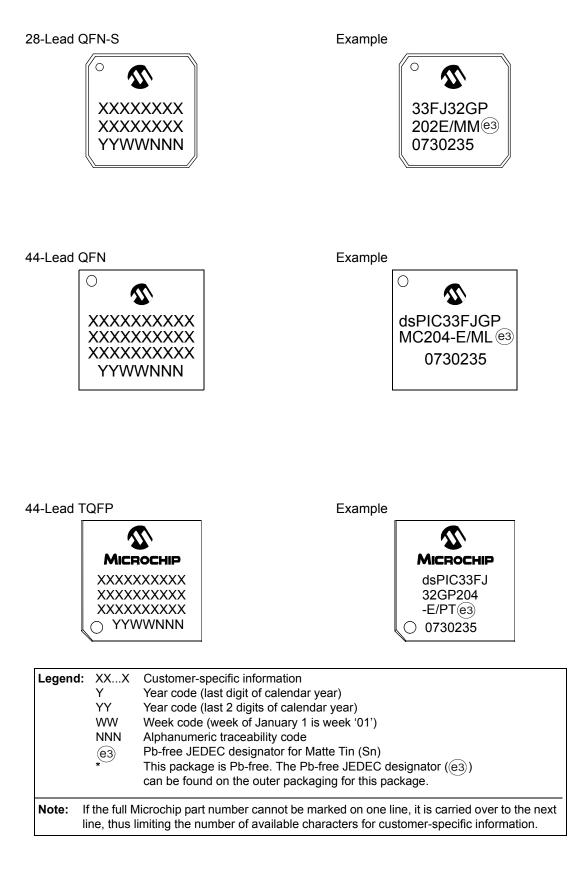
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCK clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

25.1 Package Marking Information (Continued)



Revision D (October 2009)

This revision includes minor typographical and formatting changes throughout the data sheet text.

Global changes include:

- Changed all instances of OSCI to OSC1 and OSCO to OSC2.
- Changed all instances of PGCx/EMUCx and PGDx/EMUDx (where x = 1, 2 or 3) to PGECx and PGEDx.

Changed all instances of VDDCORE and VDDCORE/VCAP to VCAP/VDDCORE

All other major changes are referenced by their respective section in the following table.

TABLE A-3: MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, 16-bit Digital Signal Controllers"	Added Note 2 to the 28-Pin QFN-S and 44-Pin QFN pin diagrams, which references pin connections to Vss.
Section 8.0 "Oscillator Configuration"	Updated the Oscillator System Diagram (see Figure 8-1).
	Added Note 1 to the Oscillator Tuning (OSCTUN) register (see Register 8-4).
Section 10.0 "I/O Ports"	Removed Table 10-1 and added reference to pin diagrams for I/O pin availability and functionality.
Section 15.0 "Serial Peripheral Interface (SPI)"	Added Note 2 to the SPIx Control Register 1 (see Register 15-2).
Section 17.0 "Universal Asynchronous Receiver Transmitter (UART)"	Updated the UTXINV bit settings in the UxSTA register and added Note 1 (see Register 17-2).
Section 22.0 "Electrical Characteristics"	Updated the Min value for parameter DC12 (RAM Retention Voltage) and added Note 4 to the DC Temperature and Voltage Specifications (see Table 22-4).
	Updated the Min value for parameter DI35 (see Table 22-20).
	Updated AD08 and added reference to Note 2 for parameters AD05a, AD06a and AD08a (see Table 22-34).

NOTES: